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FSB43004A Motion SPM[®] 45 LV Series

May 2015

Features

- UL Certified No.E209204(UL1557)
- 40 V, $R_{DS(ON)}$ =3.0 m Ω (max.) 3-phase MOSFET Inverter Module Including Control IC for Gate Drive and Protection.
- · Ceramic Substrate.
- Three Separate Open-Emitter Pins from Low-Side MOSFETs for Three-Leg Current Sensing.
- Single-Grounded Power Supply for Built-in HVIC.
- · Isolation Rating of 800 Vrms/min.

General Description FSB43004A is a Motion S

FSB43004A is a Motion SPM® 45 LV module that Fairchild developed based on low-loss PowerTrench® MOSFET technology as a compact motor drive inverter solution for small power applications supplied by low voltage battery.

Applications

Motion Control - Home Appliance / Industrial Motor.



Figure 1. Packing Drawing (Click to Activate 3D Content)

Package Marking and Ordering Information

Device	Device Marking	Package	Packing Type	Quantity
FSB43004A	FSB43004A	SPMAA-A22	Rail	14

Integrated Power Functions

• 40 V R_{DS(ON)}= 2.1 mΩ(typ.) inverter for three-phase DC / AC power conversion (please refer to Figure 3)

Integrated Drive, Protection, and System Control Functions

- For inverter high-side MOSFETs: gate drive circuit, high-voltage isolated high-speed level shifting, Under-Voltage Lock-Out (UVLO) Protection.
- For inverter low-side MOSFETs: gate drive circuit, Under-Voltage Lock-Out (UVLO) Protection.
- Fault signaling: corresponding to UV (low-side supply).
- Input interface: active-HIGH interface, works with 3.3 / 5 V logic, Schmitt-trigger input

Pin Configuration

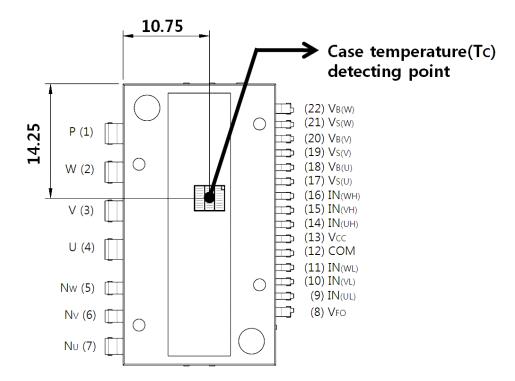


Figure 2.Top View

Pin Descriptions

Pin Number	Pin Name	Pin Description	
1	Р	Positive DC-Link Input	
2	W	W Phase Output	
3	V	V Phase Output	
4	U	U Phase Output	
5	N _W	Negative DC-Link Input	
6	N _V	Negative DC-Link Input	
7	N _U	Negative DC-Link Input	
8	V _{FO}	Fault Output	
9	IN _(UL)	PWM Input for Low-Side U Phase MOSFET Drive	
10	IN _(VL)	PWM Input for Low-Side V Phase MOSFET Drive	
11	IN _(WL)	PWM Input for Low-Side W Phase MOSFET Drive	
12	COM	Common Supply Ground	
13	Vcc	Common Supply Voltage for IC and Low-side MOSFET Drive	
14	IN _(UH)	PWM Input for High-Side U Phase MOSFET Drive	
15	IN _(VH)	PWM Input for High-Side V Phase MOSFET Drive	
16	IN _(WH)	PWM Input for High-Side W Phase MOSFET Drive	
17	V _{B(U)}	Supply Voltage for High-Side U Phase MOSFET Drive	
18	V _{S(U)}	Supply Ground for High-Side U Phase MOSFET Drive	
19	$V_{B(V)}$	Supply Voltage for High-Side V Phase MOSFET Drive	
20	V _{S(V)}	Supply Ground for High-Side V Phase MOSFET Drive	
21	V _{B(W)}	Supply Voltage for High-Side W Phase MOSFET Drive	
22	V _{S(W)}	Supply Ground for High-Side W Phase MOSFET Drive	

Internal Equivalent Circuit and Input/Output Pins

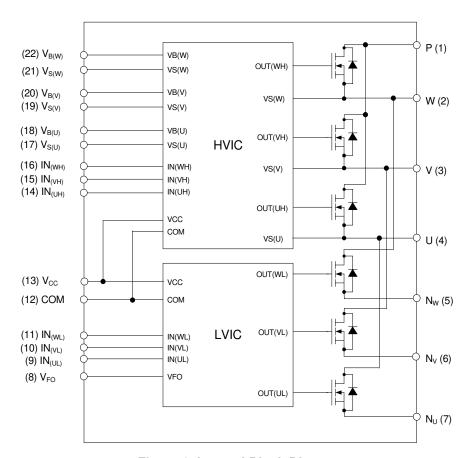


Figure 3. Internal Block Diagram

Absolute Maximum Ratings (TJ = 25°C, unless otherwise specified.)

Inverter Part

Symbol	Parameter	Conditions	Rating	unit
V _{PN}	DC Link Input Voltage Drain-Source Voltage	Applied between P - N _(U) , N _(V) , N _(W)	40	V
* ± I _D	Drain Current	$T_C = 25$ °C, $T_J \le 150$ °C	71	Α
		$T_{C} = 100^{\circ}C, T_{J} \le 150^{\circ}C$	47	Α
* ± I _{DP}	Peak Drain Current	T_{C} = 25°C, under 1ms Pulse Width, $T_{J} \le$ 150°C	180	А
* P _D	Maximum Power Dissipation	T_C = 25°C, per Chip, $T_J \le 150$ °C	31	W
TJ	Operating Junction Temperature		-40 ~ 150	°C

1st Note:

Control Part

Symbol	Parameter	Conditions	Rating	unit
V _{CC}	Supply Voltage	Applied between V _{CC} - COM	20	V
V _{BS}	Supply Voltage	Applied between $V_{B(U)}$ - $V_{S(U)}$, $V_{B(V)}$ - $V_{S(V)}$, $V_{B(W)}$ - $V_{S(W)}$	20	V
V _{IN}	PWM Signal Voltage	Applied between $IN_{(UH)}$, $IN_{(VH)}$, $IN_{(WH)}$, $IN_{(UL)}$, $IN_{(VL)}$, $IN_{(WL)}$ - COM	-0.3 ~ V _{CC} +0.3	V
V _{FO}	Fault Output Supply Voltage	Applied between V _{FO} - COM	-0.3 ~ V _{CC} +0.3	V
I _{FO}	Fault Output Current	Sink Current at V _{FO} Pin	1	mA

Total System

Symbol	Parameter	Conditions	Rating	unit
T _{STG}	Storage Temperature		-40 ~ 150	°C
V _{ISO}	Isolation Voltage	60 Hz, Sinusoidal, AC 1 Minute, Connect Pins to Ceramic Substrate	800	V _{rms}

Thermal Characteristics

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
R _{th(j-c)}	Junction to Case Thermal Resistance	Inverter MOSFET part(per 1/6 module)	-		3.92	°C/W

^{1.} Rating value of marking "*" is calculation value or design factor.

$\textbf{Electrical Characteristics} \ \, (TJ = 25^{\circ}C, \, unless \, otherwise \, specified.)$

Inverter Part

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{IN} =0 V, I _D =250 μA (2nd Notes 1)	40	-	-	V
R _{DS(ON)}	Drain-Source ON Resistance	$V_{CC} = V_{BS} = 15 \text{ V}, V_{IN} = 5 \text{ V}, I_D = 60 \text{ A}$	-	2.1	3.0	mΩ
V _{SD}	Source-Drain Diode Forward Voltage	$V_{CC} = V_{BS} = 15 \text{ V}, V_{IN} = 0 \text{ V}, I_{SD} = 60 \text{ A}$	-	0.8	-	V
t _{ON}	Switching Characteristic	$V_{PN} = 20 \text{ V}, V_{CC} = V_{BS} = 15 \text{ V}, I_D = 60 \text{ A},$	-	1750	-	ns
t _{C(ON)}		$V_{IN} = 0 \text{ V} \leftrightarrow 5 \text{ V}$, High side, Inductive Load (2nd Notes 2)	-	900	-	ns
t _{OFF}		(Zild Notes Z)	-	2600	-	ns
t _{C(OFF)}			-	800	-	ns
t _{rr}			-	60	-	ns
I _{rr}			-	3	-	Α
t _{ON}		$V_{PN} = 20 \text{ V}, V_{CC} = V_{BS} = 15 \text{ V}, I_D = 60 \text{ A},$	-	1900	-	ns
t _{C(ON)}		$V_{IN} = 0 \text{ V} \leftrightarrow 5 \text{ V}$, Low side, Inductive Load (2nd Notes 2)	-	850	-	ns
t _{OFF}		(Zild Notes Z)	-	2600	-	ns
t _{C(OFF)}			-	850	-	ns
t _{rr}]		-	60	-	ns
I _{rr}]		-	6	-	Α
I _{DSS}	Drain-Source Leakage Current	$V_{DS} = V_{DSS}$	-	-	250	μΑ

2nd Notes:

- 1. BV_{DSS} is the absolute maximum voltage rating between drain and source terminal of each MOSFET. V_{PN} should be sufficiently less than this value considering the effect of the stray inductance so that V_{DS} should not exceed BV_{DSS} in any case.
- 2. t_{ON} and t_{OFF} include the propagation delay time of the internal drive IC. $t_{C(ON)}$ and $t_{C(OFF)}$ are the switching time of MOSFET itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

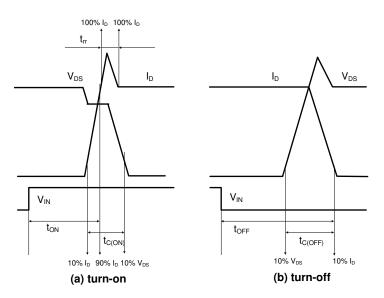


Figure 4. Switching Time Definition

Control Part

Symbol	Parameter	Co	nditions	Min.	Тур.	Max.	Unit
I _{QCC}	Quiescent V _{CC} Supply Current	V _{CC} = 15 V, V _{IN} = 0 V	V _{CC} - COM	-	-	2.75	mA
I _{QBS}	Quiescent V _{BS} Supply Current	$V_{BS} = 15 \text{ V},$ $V_{IN} = 0 \text{ V}$	$egin{array}{c} V_{B(U)} - V_{S(U)}, \ V_{B(V)} - V_{S(V)}, \ V_{B(W)} - V_{S(W)} \end{array}$	-	-	0.3	mA
V _{FOH}	Fault Output Voltage	10 kΩ to 5 V Pull-up	Normal	4.5	-	-	V
V _{FOL}			Fault	-	-	0.5	V
UV _{CCD}	Supply Circuit Under-	Detection Level		7.0	8.2	10.0	V
UV _{CCR}	Voltage Protection	Reset Level		8.0	9.4	11.0	V
UV _{BSD}		Detection Level		7.0	8.0	9.5	V
UV _{BSR}		Reset Level	Reset Level		9.0	10.5	٧
t _{FOD}	Fault-Out Pulse Width			30	-	-	μS
V _{IN(ON)}	ON Threshold Voltage	Applied between $IN_{(UH)}$, $IN_{(VH)}$, $IN_{(WH)}$, $IN_{(UL)}$,		-	-	2.6	V
V _{IN(OFF)}	OFF Threshold Voltage	$IN_{(VL)}$, $IN_{(WL)}$ - COM		0.8	-	-	V

Recommended Operating Conditions

Symbol	Parameter	Conditions	Value			Unit
Symbol	raiailletei	ei Conditions —		Тур.	Max.	Offic
V _{PN}	Supply Voltage	Applied between P - N _(U) , N _(V) , N _(W)	-	20	-	V
V _{CC}	Control Supply Voltage	Applied between V _{CC} - COM	13.5	15	16.5	V
V _{BS}	Control Supply Voltage	Applied between $V_{B(U)}$ - $V_{S(U)}$, $V_{B(V)}$ - $V_{S(V)}$, $V_{B(V)}$ - $V_{S(V)}$,	13.0	15	18.5	V
dV _{CC} /dt, dV _{BS} /dt	Control Supply Variation		-1	-	1	V/μs
V _{SEN}	Voltage for Current Sensing	Applied between N _U , N _V , N _W - COM (Including surge voltage)	-4	-	4	V

Mechanical Characteristics and Ratings

Parameter	Co		Unito				
Parameter		nditions	Min.	Тур.	Max.	Units	
Mounting Torque	Mounting Screw: - M3		0.51	0.62	0.72	N•m	
Device Flatness		See Figure 5	-	-	120	μm	
Weight			-	8.4	-	g	

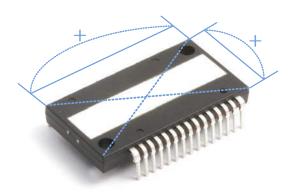
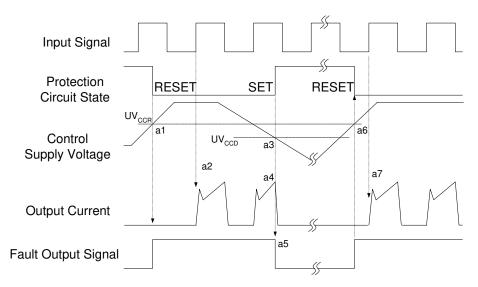


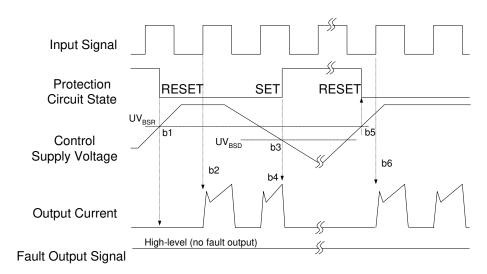
Figure 5. Flatness Measurement Position

Time Charts of Protective Function



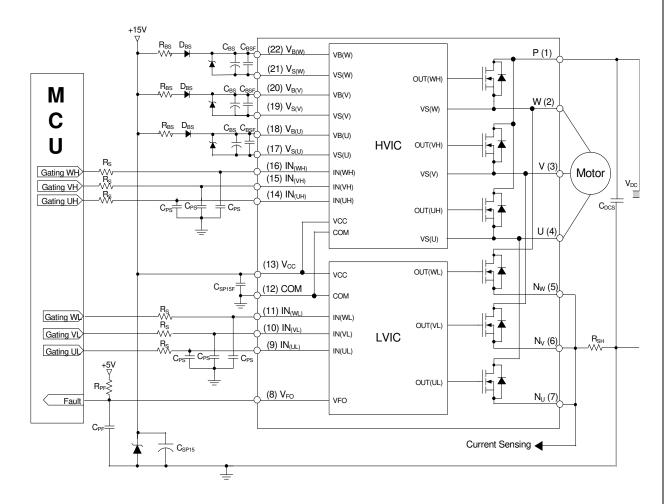
- a1 : Control supply voltage rises: after the voltage rises UV_{CCR}, the circuits start to operate when the next input is applied.
- a2: Normal operation: MOSFET ON and carrying current.
- a3 : Under-Voltage detection (UV_{CCD}).
- a4 : MOSFET OFF in spite of control input condition.
- a5 : Fault output operation starts.
- a6 : Under-Voltage reset (UV $_{CCR}$).
- a7: Normal operation: MOSFET ON and carrying current.

Figure 6. Under-Voltage Protection (Low-side)



- b1 : Control supply voltage rises: after the voltage reaches UV_{BSR}, the circuits start to operate when the next input is applied.
- b2: Normal operation: MOSFET ON and carrying current.
- b3: Under-Voltage detection (UV_{BSD}).
- b4 : MOSFET OFF in spite of control input condition, but there is no fault output signal.
- b5 : Under-Voltage reset (UV_{BSB}).
- b6: Normal operation: MOSFET ON and carrying current

Figure 7. Under-Voltage Protection (High-side)

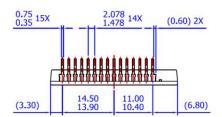


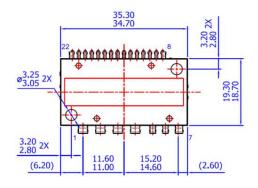
3rd Notes:

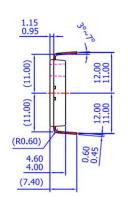
- 1. To avoid malfunction, the wiring of each input should be as short as possible. (less than $2\sim3$ cm)
- 2. V_{FO} output is open drain type. This signal line should be pulled up to the positive side of the MCU or control power supply with a resistor that makes IFO up to 1 mA.
- 3. Input signal is High-Active type. There is a 5 kQ resistor inside the IC to pull down each input signal line to GND. RC coupling circuits is recommended for the prevention of input signal oscillation. R_FC_F constant should be selected in the range 50~150ns. (Recommended R_S=100 Ω , C_{PS}=1 nF)
- 4. Each capacitors should be mounted as close to the SPM® pins as possible.
- 5. Relays are used at almost every systems of electrical equipment of home appliances. In these cases, there should be sufficient distance between the CPU and the relays.
- 6. The zener diode should be adopted for the protection of ICs from the surge destruction between each pair of control supply terminals. (Recommended zener diode=24 / 1 W)

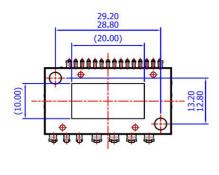
Figure 8. Typical Application Circuit

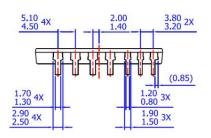
Detailed Package Outline Drawings

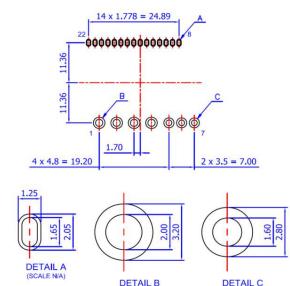












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